



## Material Content Data Sheet



Sales Product Name	TLE8366EV			Issued		28. October 2019		
MA#	MA003502964							
Package	PG-DSO-8-27			Weight*		84.31 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.728	3.24	3.24	32354	32354
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		432	
	non noble metal	iron	7439-89-6	0.728	0.86		8631	
	non noble metal	copper	7440-50-8	29.548	35.04	35.95	350449	359620
wire	noble metal	gold	7440-57-5	0.283	0.34	0.34	3356	3356
encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1155	
	plastics	epoxy resin	-	4.481	5.31		53149	
	inorganic material	silicondioxide	60676-86-0	44.130	52.35	57.78	523398	577702
leadfinish	non noble metal	tin	7440-31-5	0.695	0.82	0.82	8244	8244
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8593	8593
glue	plastics	epoxy resin	-	0.214	0.25		2533	
	noble metal	silver	7440-22-4	0.641	0.76	1.01	7598	10131
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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